佐賀大学大学院理工学研究科 AI・データサイエンス高度人材育成プログラム 博士後期課程(外国人留学生-在日) 学生募集要項

Guide for the Application for the Foreign Students of Education Program for AI and Data Science Specialists (EPAD)

(Doctor Course)

October, 2023 April, 2024

	Enrollment	Application Deadline	Examinations and Interview	Final Results
First application	October, 2023 or April, 2024	June 14, 2023	July 7, 2023	July 18, 2023
Second application	October, 2023 or April, 2024	July 27, 2023	August 24, 2023	September 12, 2023
Third application	April, 2024	November 1, 2023	November 17, 2023	December 12, 2023
Fourth application	April, 2024	January 23, 2024	February 28, 2024	March 8, 2024

* This exam schedule is scheduled as of April 20. Depending on the future spread of coronavirus (COVID-19) infection, the entrance examination schedule may be postponed. If the test cannot be conducted at Saga University due to the spread of the novel coronavirus (COVID-19), the test will be postponed and/or conducted via the Internet.

Graduate School of Science and Engineering SAGA UNIVERSITY

Personal Information Use

In accordance with enforcement of the Act on the Protection of Personal Information Held by Independent Administrative Agencies, personal information written on the application form submitted by applicants is utilized for educational purpose (including exemption of entrance and tuition fees, payment extension of entrance fee, and scholarship) as well as the selection of applicants by entrance examinations (including additional business such as statistical transaction).

Personal information possessed by Saga University is not utilized for different purposes from the aim denoted above, and is not provided to a third person without the applicant's agreement, except for the case prescribed by the item no.9 of the Act on the Protection of Personal Information Held by Independent Administrative Agencies.

Education Program for AI and Data Science Specialists (EPAD)

(Doctor Course)

October, 2023 April, 2024

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GUIDE FOR THE APPLICATION FOR THE FOREIGN STUDENTS OF EDUCATION PROGRAM FOR AI AND DATA SCIENCE SPECIALISTS (EPAD)

The Education program for AI and Data Science Specialists (EPAD) provides all lectures, seminars, and internships, etc. on AI and data science technologies in English for both foreign and Japanese students. Students from overseas can learn and study completely in Japan without a hurdle of Japanese language. The EPAD is an educational course in the Graduate School of Science and Engineering, Saga University, that started in October 2022, in order to bring up global researchers and engineers who will contribute to technological innovation in AI and data science fields. This is a call for application to a three-year Doctor Course from the academic year of October, 2023 and April, 2024.

The wisdom that mankind has created by the academic deepening has brought humanity a prosperous life through developing science and technology. To improve science and technology, it is necessary to sustain efforts from the viewpoint of AI and data science technologies. Educational study of AI and data science should be performed from the all-round and global viewpoint. The EPAD has been established in the Graduate School of Science and Engineering in order to discuss and solve AI and data science problems. The scope and goal of this EPAD is the education for students to possess an all-round insight for AI and data science from the global point of view after their completion by acquiring knowledge and thinking power.

In the Doctor Course program of the EPAD, education and research guidance of the fields are given by the Mathematical and Information Science Course, Mechanical and Electrical Energy Engineering Course, Biological and Material Engineering Course in the Graduate School of Science and Engineering. Applicants are encouraged to decide the research fields and prospective relevant supervisor(s) appearing on the List of Academic Staffs, and contact with the supervisor(s).

Students who complete the Doctor Course program of the EPAD are granted the Doctor's Degree (Doctor of Philosophy in Science or Doctor of Philosophy in Engineering). The month of entrance for foreign students is October, 2023 or April 2024 and they can enter the EPAD course immediately after completing their Master's Degree program without learning Japanese language.

OUALIFICATIONS

* For applicants who wish to enroll in April 2024, please replace "September 2023" with "March 2024".

- Nationality: Non-Japanese citizens staying in Japan can apply for this program. 1.
- Academic carrier: The following candidates may apply for admission. 2.
 - Those who have received Master's Degree from Japanese University as of September 2023. a.
 - Those who have received a Degree equivalent to Master's Degree of Japanese Universities in b. foreign country, or will receive it in foreign country as of September 2023.
 - Those who have received a Degree equivalent to Master's Degree of Japanese Universities from a c. foreign school through correspondence education in Japan, or will receive the Degree as of September 2023.
 - Those who have received a Degree equivalent to Master's Degree of Japanese Universities at d. educational institutions of the foreign country in Japan, which is designated by the Minister of Education, Culture, Sports, Science and Technology of the Japanese Government, or will receive the Degree as of September 2023.
 - Those who have been designated by the Minister of Education, Culture, Sports, Science and e. Technology of the Japanese Government.
 - f. Those who are 24 years old or more as of September 2023, and are admitted by the Graduate School of Saga University as that their academic abilities are equivalent to or higher than Master's Degree of Japanese Universities upon reviewing the submitted materials.
 - * Those who intend to apply based on the terms e or f should submit the application form to the Entrance Examination Office of Saga University one month earlier than the application deadline.
- Language proficiency: A good working level of English is required. 3.

TUITION EXPENSES

1. Entrance examination fee: 30,000 yen.

(N.B. The entrance examination fee is not necessary for the applicant who will graduate the Master Course from this University in September, 2023.)

- 2. Entrance fee: 282,000 yen.
- 3. **Tuition fee:** 267,900 Yen for each semester (scheduled). [535,800 Yen per academic year (scheduled).] Amount of due might be slightly revised depending on the decision of the administration council.

Payments must be done for each semester biannually within the beginning two months of the semester.

For the information on the tuition assistance, exemption subsidization, and scholarships is available at the Benefits section in the following pages.

SELECTION

- 1. Selection for admission shall be achieved by written and/or oral examinations on the selected major subjects and interview. All examinations and interview will be conducted in English on the date indicated on the cover page. This exam schedule is scheduled as of April . Depending on the future spread of coronavirus (COVID-19) infection, the entrance examination schedule may be postponed. If the test cannot be conducted at Saga University due to the spread of the novel coronavirus (COVID-19), the test will be postponed and/or conducted via the Internet. In this case, the detail of entrance examination will be noticed to the applicant by e-mail and examination ticket.
- 2. The final results of selection will be noticed to the applicant by a letter. It will be dispatched on **the date indicated on the cover page**.
- 3. A few students can be admitted.

ADMISSION

- 1. Date of enrollment is October 1, 2023 or April 1, 2024.
- 1. Date of registration for admission: {First and Second application} Late September, 2023

{Third and Fourth application} Late March, 2024

Details will be provided when you receive your acceptance letter. If the applicant does not register on these days, his/her admission shall be canceled.

2. Admission shall be canceled if the applicant fails to receive the Master's Degree on or before September 2023 or March, 2024.

APPLICATION

* For applicants who wish to enroll in April 2024, please replace "September 2023" with "March 2024".

- 1. Applicants should prepare the following documents to be forwarded to the Entrance Examination Office, Saga University.
 - ① **Application Form** (Form A).
 - ② Official transcript of **Master's degree** or certificate representing that the applicant will be conferred Master's degree by September 2023. Official transcript of Bachelor's degree is required in the case that the applicant will be qualified by the criterion 2-e of **QUALIFICATIONS** described above. The transcript or certificate must be sealed by the authority or sent directly from the college. Original diploma is also acceptable; in this case the examination office may exemplify the diploma and the original may be returned at the office.
 - ③ Transcripts of Academic Record issued by university authorities and its English translation. (The criteria of academic assessment should be also shown.)
 - (4) English summary of **Master Thesis** or it's equivalent if available, not exceeding four sheets of A4 size paper typed in double space. If a Master Thesis is not required by the University from which the applicant graduated, prepare a statement to this matter.
 - (5) Certificate of **Citizenship** issued by appropriate authorities.
 - 6 Recommendation and Reference

- a. A letter of **Recommendation** (Form B) from the head (Dean, in case of University) of the applicant's affiliated institution.
- b. Letter(s) of **Reference** (Form C) from those who know the applicant's research/study capability addressed to the President of Saga University.

The letters of recommendation and reference should indicate the English proficiency of the applicant. Enclose, therein, a certificate indicating the scores of TOEFL or a corresponding English Ability Test, if any.

- \bigcirc Three **Photographs** (hatless portrait), 4.5 cm \times 3.5 cm in size, taken within six months before the date of application. Two copies should be attached to the application form. One extra copy should be enclosed therein, with the applicant's name and nationality on the reverse side of the copies.
- 8 Entrance Examination Fee: 30,000 yen.
- 2. All documents should be sent by registered mail and received by the Entrance Examination Office by the deadline indicated on the cover page.

Remarks

- 1. The above documents should be type-written in English on A4 size paper.
- 2. Incomplete documents are not acceptable.
- 3. None of the documents submitted is returned to the applicant.

NOTES

- 1. The applicant will be deprived his/her entrance under the following cases:
 - a. False statements on the documents.
 - b. Violation of the pledge.
- 2. Applicants are recommended to be well acquainted with the Japanese language, culture, customs, etc. A knowledge of the Japanese language is necessary in daily life.
- 3. Applicants are expected to complete their Doctor Course Program within three years.

BENEFITS

- 1. Exemption of tuition fee from complete to 50% may be granted depending on circumstances.
- 2. There are several scholarships for private-expense foreign students. Students can apply for these scholarships.
- 3. Housing: Students can apply to Saga University International House, or low-cost apartments supported by Saga prefecture and other organizations.

CORRESPONDENCE

Any correspondence relating to the application for the EPAD should be sent by mail to the address below.

Entrance Examination Office Saga University 1 Honjo-machi Saga 840-8502, Japan E-mail: epad@mail.admin.saga-u.ac.jp

ACADEMIC STAFFS ATTENDING EPAD COURSES AND THEIR RESEARCH INTERESTS AND MAJOR FIELDS

Graduate School of Science and Engineering [Doctor course]

Mathematical and Information Science Course

Data Science

Laboratory of Data Science	Minamoto, T.
Numerical Verification, Image Processing, Signal Processing, Digital	Watermarking
Wavelet Analysis, Applied Mathematics, Data Science, Machine Lear	ning

Computer Science and Information Engineering

Laboratory of Smart System M	Iatsumae, S., Nakayama, K.
Intelligent Informatics, Artificial Intelligence	
Parallel and Distributed Algorithms	
Laboratory of Cyber Physical System	Fukuda, O., Okumura, H.
Artificial intelligence, Robotics, Intelligent sensing	
Data science, Data visualization, Biological system	
Remote sensing, Medical image processing	
Laboratory of Fundamental and Applied Informatics Hana	da, E., Hori, Y., Okazaki, Y.
Information/Comminication Systems in Clinical medici	ne/Healthcare/Welfare
Hospital Facilities, Information and Systems in Education	on, Computational Science
Information network, Network security	

Mechanical and Electrical Energy Engineering Course

Thermo-Fluid Energy Engineering

Laboratory of Thermal Engineering

...... Miyara, A., Mitsutake, Y., Kariya, K. and Ishida, K. Thermodynamics, energy conversion, power plant systems Heat exchanger, condensation, evaporation, absorption

Laboratory of Fluid Engineering......Kinoue, Y. and Shiomi, N. Turbomachinery, compressible fluid flow, effective utilization of fluid energy, multiphase flow

Material and Design Engineering

Laboratory of Mechanics of Materials, Solid and Structures

	Hasegawa, H., Mawatari, T. and Ohshima, F.
Design of machinery and machine elen	nents
Tribology of machine elements	
Surface engineering	
Laboratory of Control Engineering	Sato, K.

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C	ntral that	my robust og	ntrol, adaptive	agentral	
		DIV, IODUSI CO	muor, auapuve		
		5,	<i>,</i> 1		

Ocean Energy Engineering

Laboratory of Ocean Engineering	Imai, Y. and Murakami, T.
Wave energy conversion system, Marine hydrodyn	amics, Floating system
Laboratory of Thermal Engineering Boiling heat transfer, two-phase flow, effective up	
Laboratory of Thermal Energy Conversion Systems Ocean thermal energy conversion plant, developm system	C
Laboratory of Offshore Wind Energy Systems Rotor aerodynamic, aero-elastics, floating offshore	

Electronics, Information and Communication

Laboratory of Advanced Microwave Engineering
Toyoda, I., Tanaka, Takayuki and Nishiyama, E.
Microwave circuits
Planar antennas
Wireless power transfer
Wireless communication systems
Laboratory of Advanced Computational EngineeringItoh, H. and Fukumoto, H.
Artificial general intelligence
Adaptive robots
Educational support system
Human interface
Laboratory of Advanced Optoelectronics
Laboratory of Bionic and Cybernetic Engineering Wakuya, H.
Artificial Intelligence
Smart Robotic System
Biomedical Instrumentation
Laboratory of Photovoltaic System
Parameter estimation of photovoltaic models
Diagnosis of large-scale photovoltaic power plant

Advanced Power Electronics

Laboratory of Microwave Electronic Devices and CircuitsOishi, T.
High power and high frequency electronic devices using wide bandgap semiconduc-
tors
Device modeling technology
Laboratory of Plasma Energy Engineering Ohtsu, Y. and Ihara, S.
Plasma processing
Thin film preparation
Dry etching process
High voltage engineering
Pulsed power engineering
Plasma engineering
Laboratory of Surface and Interface Dynamics
Synchrotron light application
Electron spectroscopy
Nano-scale materials

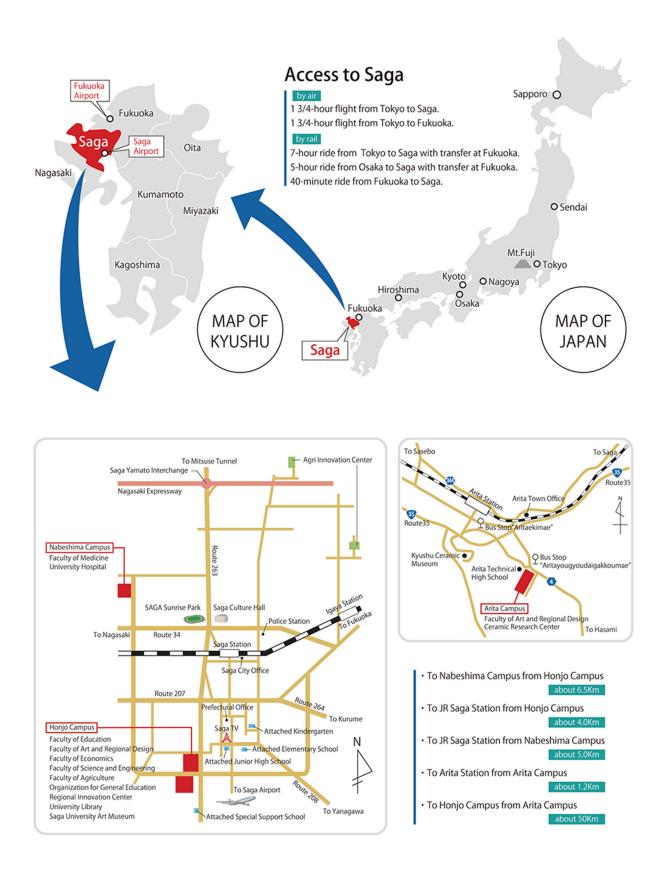
Biological and Material Engineering Course

Biomedical Engineering

Laboratory of Intelligent Control EngineeringGoto, S., Sugi, T. and Matsuda, Y.
Medical systems control
Plant systems control
Remote systems control
Mechatronic systems control and robotics
Reliability analysis for power plant
Control systems design
Laboratory of Biosensors
Intelligent-composite multisensors
Tactile sensors mimicking human perceptions
Non-invasive imaging with composite sensors
Laboratory of Applied ComputingMuramatsu, K. and Dozono, H
Numerical analysis of electromagnetic field
Optimal design of electromagnetic apparatus
Modelling of magnetic materials
Soft computing
Self-organizing maps
Laboratory of Fluid Engineering
Compressible fluid flow, effective utilization of fluid energy, multiphase flow
Laboratory of Sensing Systems
Non-destructive testing
Inverse problems in multidimensional sensing
Wave-field analysis
Biomedical sensing by ultrasound
Photonic Sensing
Nano-scale Sensing
Signal processing

Laboratory of Biomedical Sensing		
Sensing systems of biomedical engineering dynamics		
Laboratory of Robotics and Computational Intelligence		
Robotics, Mechatronics, Computational Intelligence, Machine learnin	g	

Access to Honjo Campus, Saga University



EDUCATION PROGRAM FOR AI AND DATA SCIENCE SPECIALISTS (EPAD)

GRADUATE SCHOOL OF SCIENCE AND ENGINEERING, SAGA UNIVERSITY

APPLICATION FORM

INSTRUCTIONS (記入上の注意)

- Application should be typewritten or written in Roman block capitals.
 (記入は楷書又は大文字のローマ字体を用いること。)
- Numbers should be written in Arabic figures. (数字は算用数字を用いること。)
- 3. Year should be written in the Anno Domini system. (年号はすべて西暦とすること。)
- 4. Proper nouns should be written in full and not be abbreviated. (固有名詞はすべて正式な名称とし、一切省略しないこと。)
- 5. An Examination fee of 30,000 Yen should be enclosed. (検定料 30,000 円を添えること。)
- 6. Write your name and the address within the box below for notifying the result of the selection. This box will be used for the addressing stickers.
 (合格通知書等を送付するので氏名と住所を下記欄に記入のこと。この欄は住所ラベルとして使用する。)

Name	:
Present address	:
Tel/Fax	:

Form A-1

*	受験番	号
第		

EDUCATION PROGRAM FOR AI AND DATA SCIENCE SPECIALISTS (EPAD) GRADUATE SCHOOL OF SCIENCE AND ENGINEERING, SAGA UNIVERSITY (DOCTOR COURSE)

佐賀大学大学院理工学研究科 AI・データサイエンス高度人材育成プログラム (博士後期課程)入学志願票

Co	urse					Paste a passport sized
	Mathematical and Informa	ation Scier	nce			photograph or digital
	Mechanical and Electrical	Energy E	ngineering			image taken within the
	Biological and Material Er	ıgineering				past 6 months. Write your name and nationality in
Pei	riod of Hope for Admission	: Octob	er. 2023 □An	oril. 2024		block letters on the back of the photo.
_	me of the desired supervise		· –		入すること。)	(4.5 cm×3.5 cm photo) (写真 (4.5 cm×3.5cm))
1.	Name in full, in native la	ınguage (אַ	生名(自国語))			
-	(Family name) In Roman block capitals (t name)	, (Mi	ddle name)	(Sex) □Male (男)
	In noman block capitals	(F (1)				□Female (女)
_	(Family name)	, (Firs	t name)	, (Mi	ddle name)	(Marital Status) □Single (未婚)
2.	Nationality (国籍)					□Married (既婚)
3.	Date of birth (生年月日)		,Month	,Date	,Age	(As of April 1, 2023)
4.	Present status; with the n (現職(在学大学名又は勤務先名まで			(日) attended, or	(年齢) • of the empl	oyer
5.	Present address and teleg (現住所及び電話,ファックス番号 Present address (現住所):			e number oi	r E-mail add	ress
	電話番号/FAX 番号(Telephon	e/facsimile	e number) :			
	E-mail address :					
6. 7.	Permanent address (本籍 Field of specialization stu	ıdied in th		detailed an	d specific as	possible.)
	(過去に専攻した専門分野(できるカ	ごけ具体的に診	羊細に書くこと。)			

号

	Name and Address of School (学校名及び所在地)	Year and Month of Entrance and Completion (入学及び卒業年 月)	Amount of time spent at the school attended (修学年数)	Diploma or Degree awarded,Major subject (学位・資格,専攻科目) When taking leave of absence,the period and reason. (休学した場合はその期間・理 由)
Elementary Education (初等教育)	Name (学校名)	From (入学)	years (年)	
Elementary School (小学校)	Location (所在地)	To (卒業)	and months (月)	
Secondary Education (中等教育)	Name (学校名)	From (入学)	years (年)	
Lower Secondary School (中学)	Location (所在地)	To (卒業)	and months (月)	
Upper Secondary School	Name (学校名) Location (所在地)	From (入学) To (卒業)	years (年) and months (月)	
Higher Education (高等教育)	Name (学校名)	From (入学)	years (年)	
Undergraduate Level (大学)	Location (所在地)	To (卒業)	and months (月)	
Graduate Level (大学院)	Name (学校名) Location (所在地)	From (入学) To (卒業)	years (年) and months (月)	
(以上を通算した全	ling mentioned above 学校教育修学年数) ril 1, 2023 月 1 日現在)	years(年)		

* If the blank spaces above are not sufficient for the information required, please attach a separate sheet ((注)上欄に書ききれない場合には、適当な別紙に記入して添付すること。)

9. State the titles or subjects of books or papers (including graduation thesis authored by the applicant), if any, with the name and address of publisher and the date of publication.
(著書,論文(卒業論文を含む。)があればその題名,出版社名,出版年月日,出版場所を記すこと。)

10. Employment Record: Begin with the most recent employment, if applicable. (職歴)

Name and address of organization (勤務先及び所在地)	Period of employment (勤務期間)	Position (役職名)	Type of work (職務内容)
	From To		
	From To		

11. Japanese language background, if any (日本語の学習歴)

i) Name and address of institution (学習機関及びその住所)

ii)	Period of study:	from		to		,	
	(学習期間)		Year (年) Month (月)		Year (年)Month (月)	_	Years(年間)

iii) Name of teacher (教師名)

iv) Japanese language proficiency: Evaluate your level and insert an X where appropriate in the following blank space. (日本語能力を自己評価のうえ,該当欄に×印を記入すること。)

	Excellent(優)	Good(良)	Fair(可)	Poor(不可)
Reading (読む能力)				
Writing (書く能力)				
Speaking (話す能力)				

12. Foreign language proficiency: Evaluate your level and insert an X where appropriate in the following blank space. (外国語能力を自己評価のうえ,該当欄に×印を記入すること。)

	Excellent(優)	Good(良)	Fair(可)	Poor(不可)
English(英語)				
French(仏語)				
German(独語)				
Spanish(西語)				

13. Family background (家族状況)

Name(氏名)	Relationship (続柄)	Age (年齢)	Occupation (職業)
	(旅江作り)	(中断)	(城未)

14. Accompanying Dependents (Provide the following information if you plan to bring any family members to Saga, Japan.) 同伴家族欄 (佐賀に来る場合, 同伴予定の家族がいる場合に記入すること。) * He/She is advised to take into consideration various difficulties and the great expense that will be involved in finding living quarters. Therefore, those who wish to be accompanied by their families are advised to <u>come alone first</u> and let their dependents come after suitable accommodation has been found.

(注)家族用の宿舎をみつけることは相当困難であり賃貸料も非常に割高になるのであらかじめ承知されたい。このため,留学生はまず単身で佐賀に来て,適当な宿舎をみつけた後,家族を呼び寄せること。

Name (氏 名)	Relationship (続 柄)	Age (年 齢)

15. Person to be notified in applicant's home country in case of emergency: (緊急の際の母国の連絡先)

- i) Name in full(氏名):
- ii) Address: with telephone number, facsimile number, e-mail address:(住所:電話番号,ファックス番号及び e-mail アドレスを記入のこと。)

現住所(present address):

電話番号/FAX 番号(Telephone/facsimile number):

E-mail address :

iii) Occupation (職業):

iv) Relationship (本人との関係):

16. Immigration Records to Japan. (日本への渡航記録)

Date (日付)	Purpose (渡航目的)
From To	
From To	

17. Are you also applying to EPAT (another program at Saga University)? (あなたは「EPAT (佐賀大学のもう一つのプログラム)」にも出願していますか?)

 \Box Yes, \Box No.

18. (Please fill in only if you answered "Yes" in 17.) Which is your first choice, "EPAD" or "EPAT"? ((17.で「はい」と答えた方のみ記入してください)あなたは「EPAD」と「EPAT」のどちらが第 1 志望ですか?) □ EPAD, □ EPAT.

Date of application(申請年月日):

Applicant's signature(申請者署名):

Applicant's name (in Roman

block capitals)(申請者氏名):

Form A –	- 2				* 受 第	於 験番号	号
	AD] Graduate	GRAM FOR AI AND I (DOCTOR MISSION TICKET FO School of Science and 学研究科 AI・データサイコ 受騎	COURSE) DR THE EX Engineerin ニンス高度人材	AMINATIO ng, Saga Un	N iversity		
1. Course (志望コース)			[
	cal and Information				Photo		
□ Mechanical	and Electrical	Energy Engineering			$4.5 \mathrm{cm} imes$	3.5cm	
-	nd Material Er for Admission	ngineering : □October, 2023 □	April. 2024		Taken v months.		
$2. Sex \square$	Male (男)	□ Female (女)					
3. Name in fu	ill, in native la	nguage(氏名(自国語	((†				
(Family nam In Roman blo		(First name) ローマ字)	(Middle	e name)			
(Family nam	e) ,	(First name)	, (Middle	e name)			
		(切り)取	り 線))	領収番	号※第	Ę
	納 付 EXAMINAT	書 ON FEE			収証 ECEIPT	書	
※第 号	受験者氏名 (Applicant's Name)			¥ 30),000		
2023 年度	研究科名 (Graduate Course)	理工学研究科		日本円に限 (JAPANES		ENCY)	
2023 中度	専攻名 (Department)	理工学専攻		ただし,入 (EXAMINA		EE)	
¥ 30,0 ただし、2]に限る ANESE CURRENCY)		※西暦受験者氏名(Applicant)		月	日 L
(EXAMINA	TION FEE)						様
※西暦	年 月	日 領収		国立大学	学法人佐賀	員大学	
領収証書及び編	内付書の氏名欄け	必ず明記すること。					

※印の欄は、記入しないこと。 (Applicant should not fill in except his/her name, Graduate Course and Department.)

受験番号

Form B (在日)

推 薦 書 LETTER OF RECOMMENDATION

佐賀大学長 様 To: President of Saga University

	被推薦者 Recommendee 氏名 Full Name: 生年月日 Date of Birth: 国籍 Nationality:	
	日付 Date: (month) (date) (year)	
推薦者 Recommender 署名 Signature: 氏名 Print Name:		
役職 Title and Institution (or Company):		
現住所 Present Address:		
E メールアドレス E-mail Address:		

Form C (在日)

証明書 LETTER OF REFERENCE

佐賀大学長 様 To: President of Saga University

	被証明者 Referenced person 氏名 Full Name: 生年月日 Date of Birth: 国籍 Nationality:	
	日付 Date: (month) (date) (year)	
証明者 Reference person 署名 Signature: 氏名 Print Name:		
役職 Title and Institution (or Company):		
現住所 Present Address:		
E メールアドレス E-mail Address:		